



Material Content Data Sheet



Sales Product Name		TLE4997A8		Issued		24. January 2018		
MA#		MA001216352						
Package		PG-TDSO-8-1		Weight*		66.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.268	3.39	3.39	33932	33932
leadframe	non noble metal	zinc	7440-66-6	0.062	0.09		926	
	non noble metal	tin	7440-31-5	0.077	0.12		1157	
	non noble metal	chromium	7440-47-3	0.093	0.14		1389	
wire	non noble metal	copper	7440-50-8	30.717	45.95	46.30	459510	462982
	noble metal	gold	7440-57-5	0.046	0.07	0.07	681	681
encapsulation	organic material	carbon black	1333-86-4	0.064	0.10		958	
	plastics	epoxy resin	-	3.458	5.17		51730	
	inorganic material	silicondioxide	60676-86-0	28.496	42.63	47.90	426292	478980
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7438	7438
plating	noble metal	silver	7440-22-4	0.793	1.19	1.19	11863	11863
glue	plastics	acrylic resin	-	0.069	0.10		1031	
	plastics	epoxy resin	-	0.069	0.10		1031	
	inorganic material	silicondioxide	60676-86-0	0.138	0.21	0.41	2062	4124
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com